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2015年3月

FGH60T65SHD 650 V, 60 A 场截止沟槽 IGBT

特性

- 最大结温: T_J=175°C • 正温度系数,易于并联运行
- 高电流能力
- 低饱和电压: V_{CE(sat)} =1.6 V(典型值)@ I_C = 60 A
- 器件 100% 经过 I_{LM}(1) 测试
- 高输入阻抗
- 快速开关
- 紧密的参数分布
- 符合 RoHS 标准

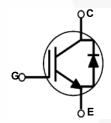
概述

Fairchild 场截止第三代 IGBT 新系列采用创新型场截止 IGBT 技 术,为光伏逆变器、UPS、焊机、通讯、ESS 和 PFC 等低导通 和开关损耗至关重要的应用提供最佳性能。

应用

• 太阳能逆变器、 UPS、电焊机、电信、 ESS 、 PFC





绝对最大额定值 T_C = 25℃ 除非另有说明

符号	描述		FGH60T65SHD_F155	单位
V _{CES}	集电极一发射极之间电压		650	V
V	栅极一发射极间电压		± 20	V
V_{GES}	瞬态栅极-发射极间电压		± 30	V
Ic	集电极电流	@ T _C = 25°C	120	Α
	集电极电流	@ T _C = 100°C	60	Α
I _{LM (1)}	集电极脉冲电流	@ T _C = 25°C	180	Α
I _{CM (2)}	集电极脉冲电流		180	
I _F	二极管正向电流	@ T _C = 25°C	60	Α
'F	二极管正向电流	@ T _C = 100°C	30	Α
I _{FM}	二极管最大正向脉冲电流		180	Α
P _D	最大功耗	@ T _C = 25°C	349	W
	最大功耗	@ T _C = 100°C	174	W
T _J	工作结温		-55 至 +175	°C
T _{stg}	存储温度范围		-55 至 +175	°C
TL	用于焊接的最大引脚温度,距离外	売 1/8",持续 5 秒	300	°C

注: 1. V_{CC} = 400 V, V_{GE} = 15 V, I_C =180 A, R_G = 20 Ω, 感性负载

2. 重复额定值: 脉宽受最大结温限制

热性能

符号	参数	FGH60T65SHD_F155	单位	
$R_{\theta JC}(IGBT)$	结至外壳热阻最大值	0.43	°C/W	
$R_{\theta JC}(Diode)$	结至外壳热阻最大值	1.25	°C/W	
$R_{\theta JA}$	结至环境热阻最大值	40	°C/W	

封装标识与定购信息

器件编号		顶标	封装	包装方法	卷尺寸	带宽	每管数量
	FGH60T65SHD_F155	FGH60T65SHD	TO-247 G03	塑料管	不适用	不适用	30

IGBT 电气特性 T_C = 25°C 除非另有说明

符号	参数	测试条件	最小值	典型值	最大值	单位
关断特性						
BV _{CES}	集电极一发射极击穿电压	V_{GE} = 0V, I_C = 1 mA	650	-	-	V
ΔBV _{CES /} ΔT _J	击穿电压温度系数电压	I _C = 1 mA, 参考 25°C 数值	-	0.6	-	V/°C
I _{CES}	集电极切断电流	$V_{CE} = V_{CES}$, $V_{GE} = 0$ V	-	-	250	μΑ
I _{GES}	G-E 漏电流	$V_{GE} = V_{GES}, V_{CE} = 0 V$	-	-	±400	nA
导通特性						
V _{GE(th)}	G-E 阈值电压	I_C = 60 mA, V_{CE} = V_{GE}	4.0	5.5	7.5	V
		I _C = 60 A, V _{GE} = 15 V	-	1.6	2.1	V
V _{CE(sat)}	集电极一发射极间饱和电压	I _C = 60 A, V _{GE} = 15 V, T _C = 175°C	-	2.14	-	٧
动态特性						
C _{ies}	输入电容		-	2980	-	pF
C _{oes}	输出电容	$V_{CE} = 30 \text{ V}, V_{GE} = 0 \text{ V},$ f = 1 MHz	-	110	-	pF
C _{res}	反向传输电容	1 - 1 1011 12	-	36	-	pF
开关特性						
t _{d(on)}	导通延迟时间		- /	26	-	ns
t _r	上升时间		-	48	-	ns
t _{d(off)}	关断延迟时间	V _{CC} = 400 V, I _C = 60 A,	-	87	-	ns
t _f	下降时间	$R_G = 6 \Omega, V_{GE} = 15 V,$	-	47	-	ns
E _{on}	导通开关损耗	感性负载,T _C = 25°C	-	1.69	-	mJ
E _{off}	关断开关损耗		-	0.63	-	mJ
E _{ts}	总开关损耗		-	2.32	- /	mJ
t _{d(on)}	导通延迟时间		-	25	- \	ns
t _r	上升时间			60	-	ns
t _{d(off)}	关断延迟时间	V _{CC} = 400 V, I _C = 60 A,	-	93	-	ns
t _f	下降时间	R _G = 6 Ω, V _{GE} = 15 V, 感性负载, T _C = 175°C	-	72	-	ns
E _{on}	导通开关损耗	您往贝羝, I _C = 1/3 U	-	2.54	-	mJ
E _{off}	关断开关损耗		-	1.04	-	mJ
E _{ts}	总开关损耗		-	3.58	-	mJ

IGBT 电气特性 (接上页)

符号	参数	测试条件	最小值	典型值	最大值	单位
Q_g	总栅极电荷	V _{CE} = 400 V, I _C = 60 A, V _{GE} = 15 V	-	102	-	nC
Q _{ge}	栅极一发射极间电荷		-	18.4	-	nC
Q _{gc}	栅极一集电极间电荷		-	37.5	-	nC

二极管电气特性 T_C = 25°C 除非另有说明

符号	参数	测试条件		最小值	典型值	最大值	单位
V _{FM}	二极管正向电压	I _F = 30 A	T _C = 25°C	-	2.3	2.7	V
			T _C = 175°C	-	1.9	-	·
E _{rec}	反向恢复电能		T _C = 175°C	-	50	-	uJ
t	rr 二极管反向恢复时间	I _F =30 A, dI _F /dt = 200 A/μs	T _C = 25°C	-	34.6	-	ns
^t rr			T _C = 175°C	-	197	-	
Q _{rr}	二极管反向恢复电荷		T _C = 25°C	-	58.6	-	nC
~11	一次自众内区交电问		T _C = 175°C	-	810	-	0

图 1. 典型输出特性

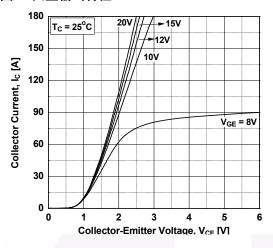


图 2. 典型输出特性

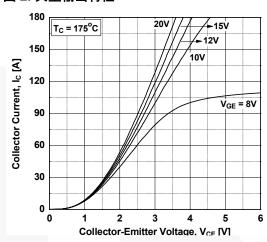


图 3. 典型饱和电压特性

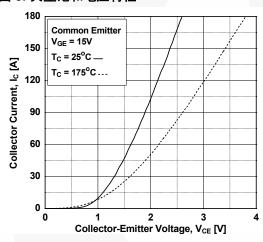


图 4. 饱和电压与可变电流强度下壳温的关系

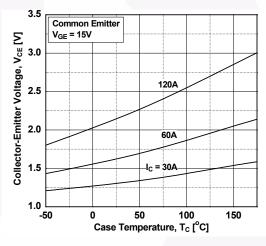


图 5. 饱和电压与 V_{GE} 的关系

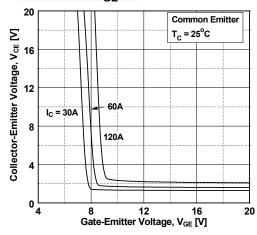


图 6. 饱和电压与 V_{GE} 的关系

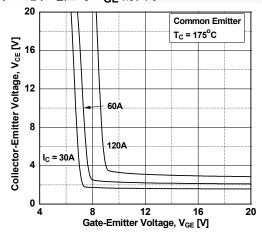


图 7. 电容特性

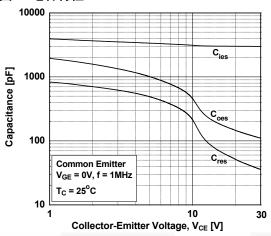


图 8. 栅极电荷特性

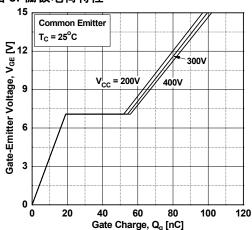


图 9. 导通特性与栅极电阻的关系

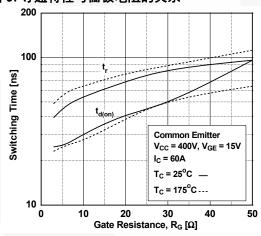


图 10. 关断特性与栅极电阻的关系

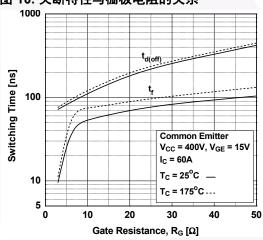


图 11. 开关损耗与栅极电阻的关系

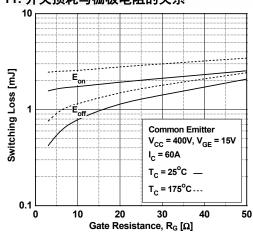


图 12. 导通特性与集电极电流的关系

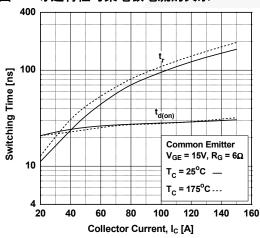


图 13. 关断特性与集电极电流的关系

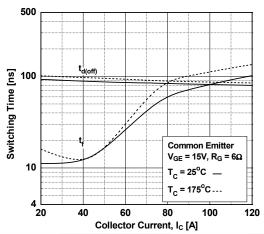


图 14. 开关损耗与集电极电流的关系

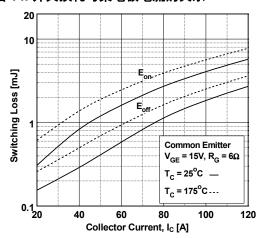


图 15. 负载电流与频率的关系

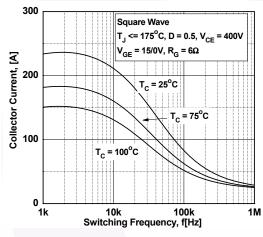


图 16. SOA 特性

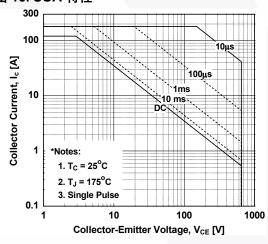


图 17. 正向特性

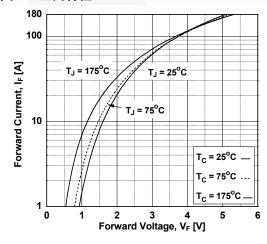


图 18. 反向恢复电流

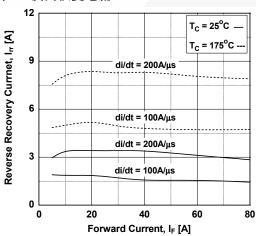


图 19. 反向恢复时间

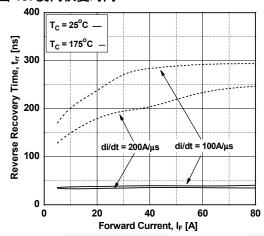


图 20. 存储电荷

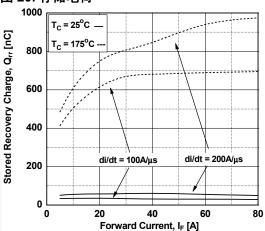


图 21. IGBT 的瞬态热阻

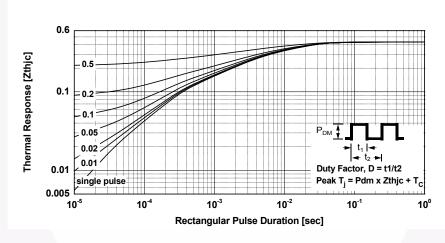
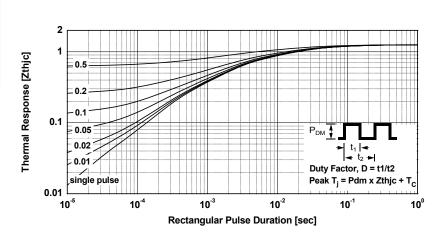
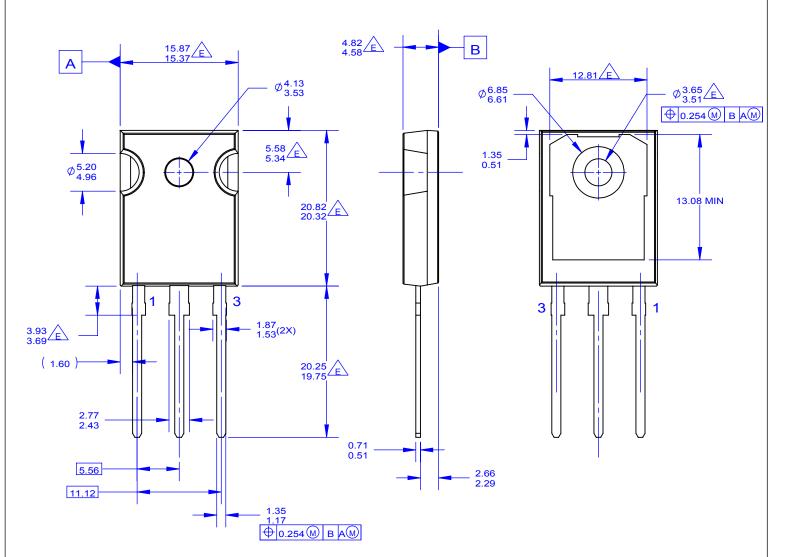


图 22. 二极管瞬态热阻抗





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